

19.10.2018

PCN

Verlagerung der Backend-Fertigung von EPCOS Drucksensorelementen

Zur Erhöhung der Produktionskapazität wird die Backend-Fertigung (Vereinzeln, Wafer-Testmessung, optische Inspektion) von EPCOS Drucksensorelementen der Serien B58600* und B58601* von Stahnsdorf bei Berlin zum Standort Beeskowdamm in Berlin verlagert. Dies geschieht in zwei Phasen:

Verlagerungsphasen	Geplanter Zeitraum
1. Freigabe der neuen Produktionsstätte am Beeskowdamm mit dupliziertem Maschinenaufbau für die Backend-Fertigung (Prozessfreigabe mit PPAP an Kunden).	November 2018 bis Ende Februar 2019
2. Verlagerung der Ausrüstung von Stahnsdorf an den Standort am Beeskowdamm (interne Prozessfreigabe inklusive Information an Kunden). Schließung der Backend-Fertigung in Stahnsdorf.	Mai 2019

Erste Lieferungen aus dem Standort am Beeskowdamm sind ab 1. März 2019 (Phase 1) geplant.

Anlage PCN (ID No. T122/0205)

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Kunden wenden sich bei Fragen bitte direkt an ihren Ansprechpartner im Vertrieb.

TDK Electronics AG

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Product / Process Change Notification

1. ID No.: T122/0205		2. Date of announcement: October 19, 2018	
3. Product / product group: EPCOS pressure sensor elements	Old ordering code: B58600*, B58601*	New ordering code: No change	Customer part number:
4. Description of change: Relocation of pressure sensor element backend production (dicing, wafer test measurement, optical inspection) in two phases: Phase 1: Release of new production location Beeskowdamm with duplicate machineries for backend production processes (process release with PPAP to customer). November 2018 to end of February 2019 Phase 2: Relocation of equipment from Stahnsdorf to Beeskowdamm (internal process releases with information note to customer). Closing of backend production in Stahnsdorf. May 2019			
5. Effect on the product or for the customer (benefit, quality, specification, lead time): Capacity extension established for production ramp-up. Depending on approval process there will be no or limited effect on lead time as this is conducted in two phases, doubling of existing equipment at new location additional to running production.			
6. Quality assurance measures / risk assessment: 1. Machine capability studies and process releases acc. to EPCOS Corporate Guide Lines and IATF 16949 (pressure sensing element backend processes). 2. Process studies and equipment release (pressure sensing element backend processes). 3. Product validation in a pressure transducer housing (pressure sensing element). 4. Outgoing test, i.e. AOI and outgoing inspection (for pressure sensing element).			
7. Scheduled date of change: Phase 1: Internal release finished by End of February 2019 Phase 2: Relocation of equipment in May 2019			
8. Estimated date of first delivery of changed product: Possible from March 2019 (Phase 1) If TDK Electronics AG does not receive notification to the contrary within a period of 10 weeks, TDK Electronics AG assumes that the customer agrees to the change. For an interim period we cannot rule out that old as well as new products will be shipped.			
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Customer feedback	
Customer acknowledgement	Signature